

# SU1A THRU SU1M

## SINTERED GLASS JUNCTION SURFACE MOUNTED RECTIFIER

VOLTAGE: 50 TO 1000V

CURRENT: 1.0A

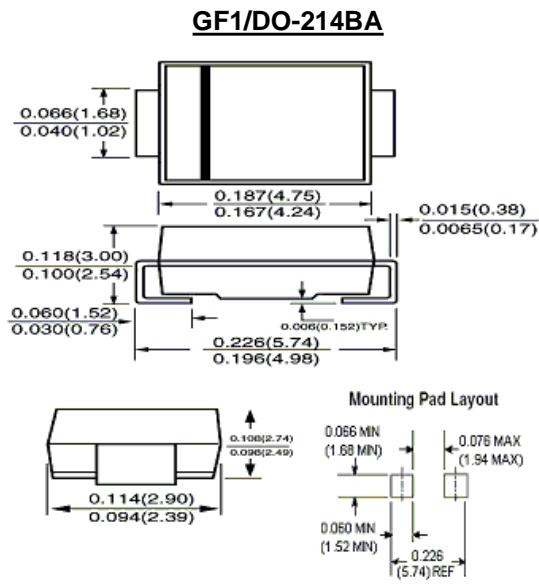


### FEATURE

Ideal for surface mount automotive applications  
High temperature metallurgically bonded construction  
Capability of meeting environmental standard of  
MIL-S-19500  
Fast switching for high efficiency  
High temperature soldering guaranteed  
450°C/5sec at terminal  
Complete device submersible temperature of  
265°C for 10 seconds in solder bath

### MECHANICAL DATA

Terminal: Solder plated, solderable per  
MIL-STD 202, method 208C  
Case: Molded with UL-94 class V-0 recognized Flame  
Retardant Epoxy over Glass  
Polarity: color band denotes cathode end  
Mounting position: any



Dimensions in inches and (millimeters)

### MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Rating at 25°C ambient temperature unless otherwise specified.

	SYMBOL	SU 1A	SU 1B	SU 1D	SU 1G	SU 1J	SU 1K	SU 1M	Units
Maximum Recurrent Peak Reverse Voltage	V <sub>rrm</sub>	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	V <sub>rms</sub>	35	70	140	280	420	560	700	V
Maximum DC blocking Voltage	V <sub>dc</sub>	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified current T <sub>L</sub> =120°C	I <sub>f(av)</sub>				1.0				A
Peak Forward Surge Current 8.3ms single half sine-wave superimposed on rated load (JEDEC method)	I <sub>fsm</sub>				30.0				A
Maximum Forward Voltage at 1.0A	V <sub>f</sub>		1.0		1.4		1.7		V
Maximum full load reverse current full cycle average Ta = 55°C	I <sub>r(av)</sub>				50.0				μ A
Maximum DC Reverse Current Ta =25°C at rated DC blocking voltage Ta =125°C	I <sub>r</sub>				10.0				μ A
Maximum Reverse Recovery Time (Note1 )	T <sub>rr</sub>		50			75			nS
Typical Junction Capacitance (Note 2)	C <sub>j</sub>			8.5					pF
Typical Thermal Resistance (Note 3)	R(-) <sub>JA</sub> R(-) <sub>JL</sub>			85.0					°C / W
Storage and Operating Junction Temperature Range	T <sub>stg</sub> , T <sub>j</sub>			28.0					°C

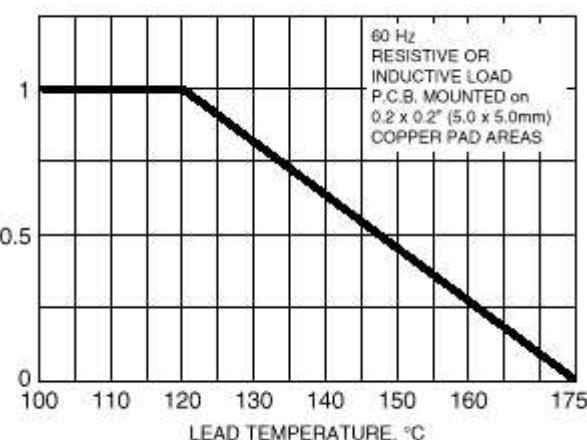
Note:

1. Reverse Recovery Condition I<sub>f</sub> =0.5A, I<sub>r</sub> =1.0A, I<sub>rr</sub> =0.25A
2. Measured at 1.0 MHz and applied V<sub>r</sub>=4.0V
3. Thermal Resistance from Junction to Ambient and from junction to lead, P.C.B. Mounted on 0.2×0.2" (5.0×5.0mm) copper pad areas<sup>1</sup>

## RATINGS AND CHARACTERISTIC CURVES SU1A THRU SU1M

AVERAGE FORWARD RECTIFIED CURRENT,  
AMPERES

FIG. 1 - FORWARD CURRENT DERATING CURVE



PEAK FORWARD SURGE CURRENT,  
AMPERES

FIG. 2 - MAXIMUM NON-REPETITIVE PEAK  
FORWARD SURGE CURRENT

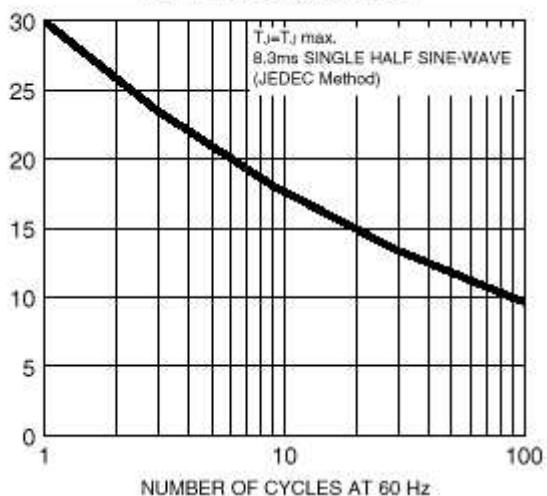
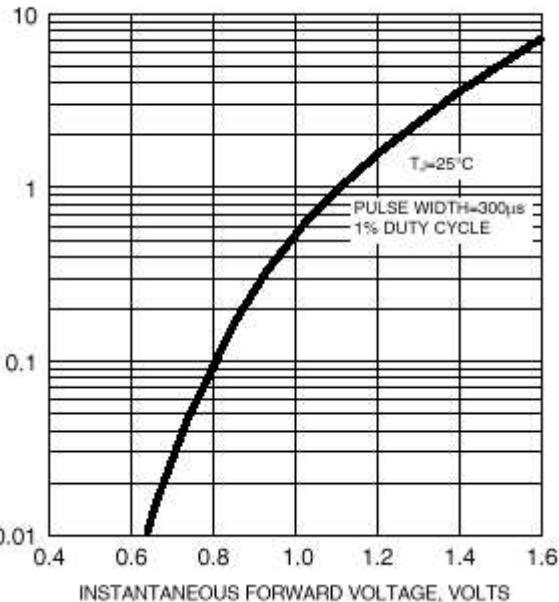


FIG. 3 - TYPICAL INSTANTANEOUS FORWARD  
CHARACTERISTICS

INSTANTANEOUS FORWARD CURRENT,  
AMPERES



INSTANTANEOUS REVERSE CURRENT,  
MICROAMPERES

FIG. 4 - TYPICAL REVERSE CHARACTERISTICS

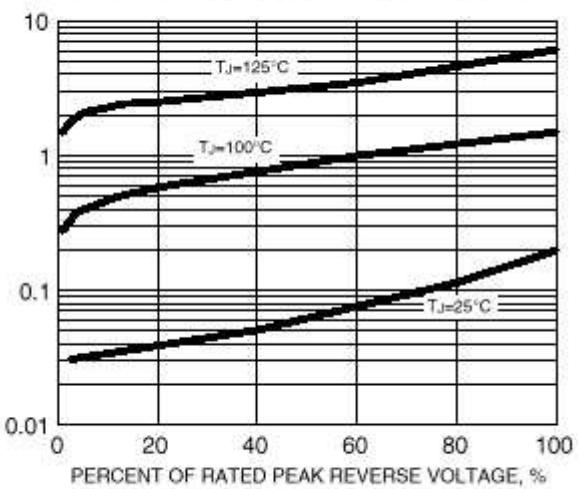


FIG. 5 - TYPICAL JUNCTION CAPACITANCE

JUNCTION CAPACITANCE, pF

